N-Channel Enhancement Mode Field Effect Transistor

Product Summary

- V_{DS} 60V
- I_D 85A
- $R_{DS(ON)}$(at V_{GS}=10V) 5.3mΩ
- 100% EAS Tested
- 100% V_{DS} Tested

General Description

- Split gate trench MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low $R_{DS(ON)}$
- Moisture Sensitivity Level 1
- Epoxy Meets UL 94 V-0 Flammability Rating
- Halogen Free
- Part no. with suffix "Q" means AEC-Q101 qualified

Applications

- Power switching application
- Uninterruptible power supply
- DC-DC convertor

=100

Junction and Storage Temperature Range

■Thermal resistance

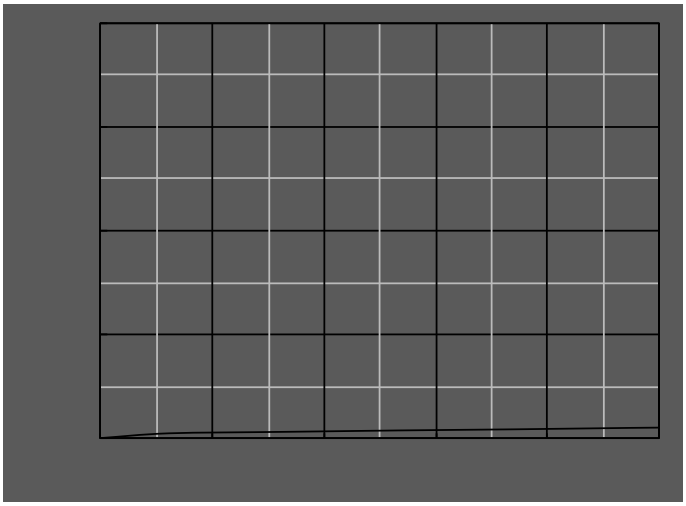
Parameter
Thermal Resistance Junction-to-Ambient D

YJG85G06HQ F1 YJG

■ Absolute Maximum Ratings (T_A=25 unless otherwise noted)

Parameter		Symbol	Limit	Unit
Drain-source Voltage		V_{DS}	60	V
Gate-source Voltage		V_{GS}	±20	V
Drain Current	T_A=25	I_D	15	A
	T_A=100		10	
	T_C=25		85	
	T_C =100		60	
Pulsed Drain Current A		I_{DM}	300	A

■Typical Electrical and Thermal Characteristics Diagrams



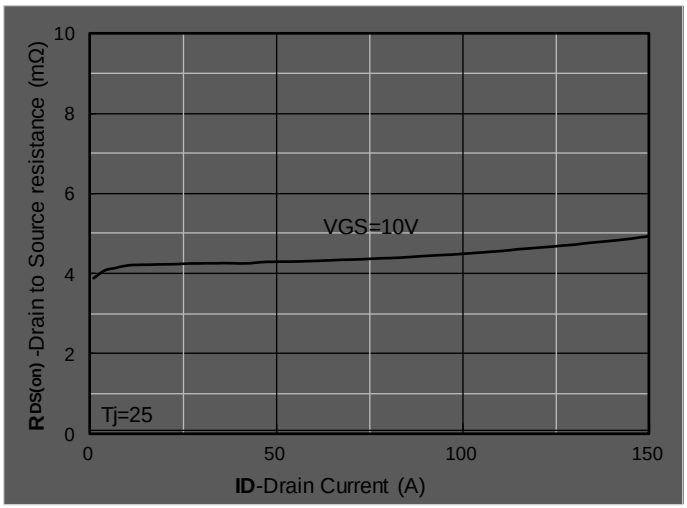


Figure 7. $R_{DS(on)}$ VS Drain Current

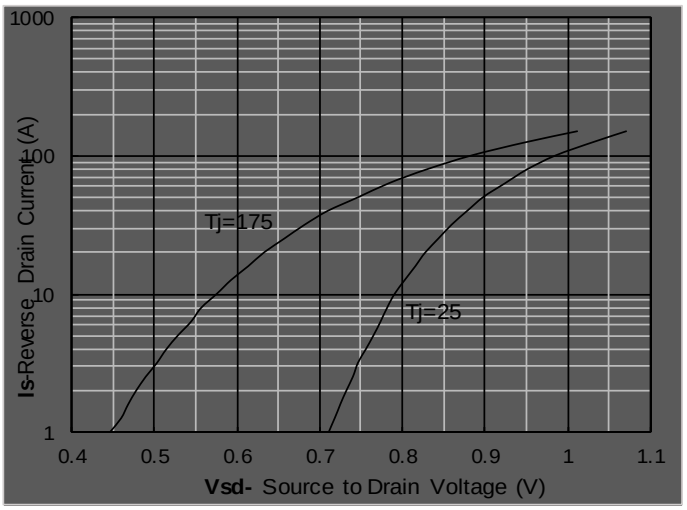
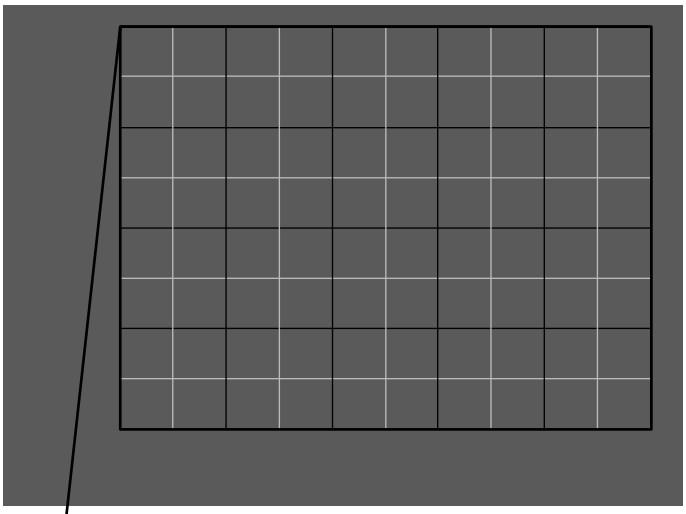
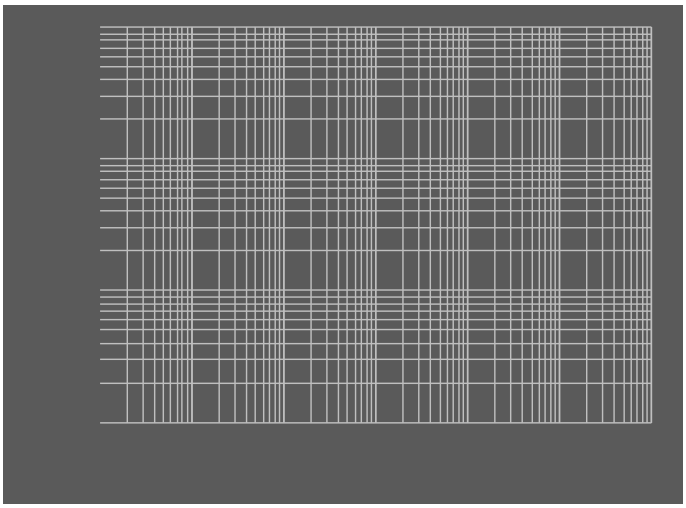


Figure 8. Forward characteristics of reverse diode





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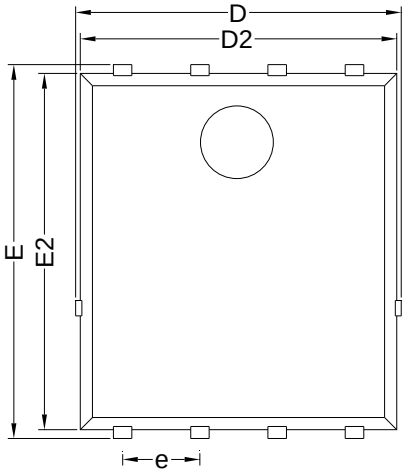
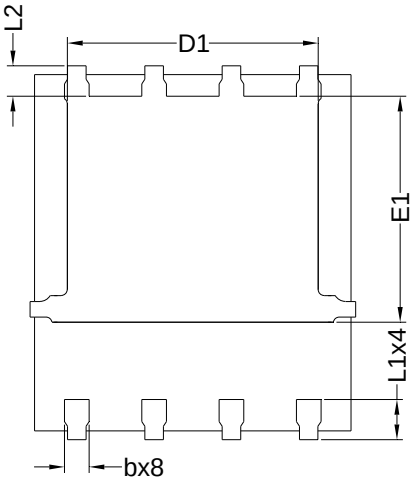
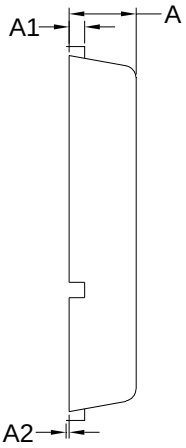
■ PDFN5060-8L-B-1.1MM Package information



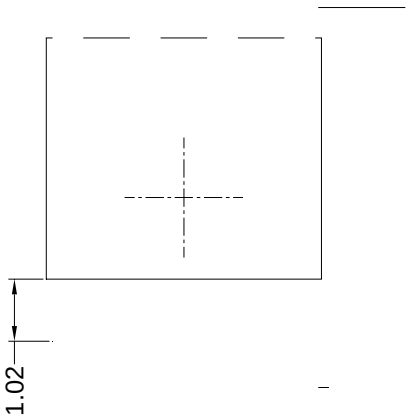
Top View



Bottom View



Side View



Suggested Solder Pad Layout
Top View

SYMBOL	MILLIMETER		
	MIN	NOM	MAX
D	5.15	5.35	5.55
E	5.95	6.15	6.35
A	1.00	1.10	1.20
A1		0.254 BSC	
A2			0.10
D1	3.92	4.12	4.32
E1	3.52	3.72	3.92
D2	5.00	5.20	5.40
E2	5.66	5.86	6.06
E3		0.254 REF	
E4		0.21 REF	
L1	0.56	0.66	0.76
L2		0.50 BSC	
b	0.31	0.41	0.51
e		1.27 BSC	

Note:
1.Controlling dimension:in millimeters.
2.General tolerance:±0.10mm.
3.The pad layout is for reference purposes only.

Disclaimer

The information presented in this document is for reference only. Ya ' ` V